

**REMARKS**

Claims 61 and 72 have been amended. Claims 61-80 remain pending in the application. Applicant respectfully requests reexamination and reconsideration of the application in light of the amendments and the following remarks.

Claims 61-80 have been rejected as unpatentable in view of US Patent No. 5,874,662 ("Eldridge") in combination with US Patent No. 5,789,930 ("Isaacs"). To the extent this rejection might be applied to the claims as amended, Applicants respectfully traverse these rejections.

Applicants have amended the claims to specify that the "bond pads" are disposed in a first predetermined pattern on the "first electronic component" and the "special contact pads" are disposed in a second predetermined pattern also on the "first electronic component." Thus, the formation of bond pads in first predetermined locations and the formation of special contact pads in second predetermined locations is done purposefully. That is, each bond pad is purposefully formed at its location and of a different size than each special bond pad, which is likewise purposefully formed at its location. In contrast, as acknowledged by the Examiner, the contact bumps on the Isaacs integrated circuit are not purposefully made to be different sizes; rather, the different sizes arise solely due to manufacturing imprecision. Thus, the locations of the bumps in Isaacs having a particular size are random. Therefore, Isaacs does not teach or suggest forming bumps of one size at first predetermined locations and forming bumps of a different size at second predetermined locations.

It follows from the above discussion that independent claims 61 and 72 (as well as their dependent claims) patentably distinguish over Eldridge and Isaacs because neither reference teaches or suggests bond pads of a first size disposed in a first predetermined pattern and bond pads of a second size disposed in a second predetermined pattern.

It should be noted that providing two differently sized pads on an electronic component provides advantages. For example, the smaller pads may allow for the use of smaller electrostatic discharge protection circuits than the larger pads. Indeed, electrostatic discharge protection may be dispensed with for the smaller pads. Similarly, the smaller pads may allow for the use of smaller input/output buffer circuitry or smaller

driver circuitry. As another example, the location of smaller pads on the electronic component is usually less restricted than larger pads.

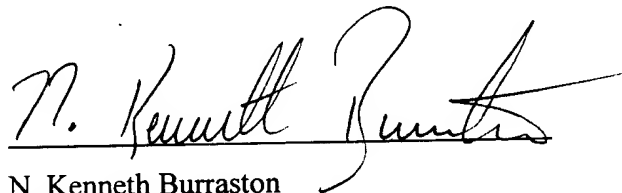
In view of the foregoing, Applicants respectfully submit that all claims pending in the application patentably distinguish over the cited and applied references and are in condition for allowance. If the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at (925) 456-3915.

Although Applicant believes that all necessary extensions of time have been requested and fees have been authorized in papers filed herewith, Applicants hereby petition the Director for any extension of time deemed necessary for acceptance of this paper, and Applicants authorize the Director to charge any fee due in connection with the filing of this paper to Deposit Account No. 50-0285 (order no. P60D4-US).

Respectfully submitted,

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**Version With Markings To Show Changes Made**

61. (Twice Amended) A socket for releasably connecting a first electronic component to a second electronic component, comprising:

a first plurality of resilient contact structures extending from a surface of a support substrate, the first plurality of resilient contact structures configured to make electrical connections with a plurality of bond pads disposed in a first predetermined pattern on the first electronic component;

a second plurality of resilient contact structures extending from the surface of the support substrate, the second plurality of resilient contact structures configured to make electrical connections with a plurality of special contact pads disposed in a second predetermined pattern on the first electronic component, wherein said special contact pads are smaller than said bond pads; and

a plurality of contact structures disposed on another surface of the support substrate for making electrical contact with said second electronic component, ones of the contact structures are connected to ones of the first plurality of resilient contact structures, and ones of the contact structures are connected to ones of the second plurality of resilient contact structures.

72. (Amended) A socket comprising:

a substrate;

a first plurality of resilient contact means for making electrical connections between terminals on a first surface of said substrate and bond pads disposed in a first predetermined pattern on a first electronic component;

a second plurality of resilient contact means for making electrical connections between terminals on said first surface of said substrate and special contact pads disposed in a second predetermined pattern on said first electronic component, wherein said special contact pads are smaller than said bond pads;

a third plurality of contact means for making electrical connections between terminals on a second surface of said substrate and a second electronic component;

means for electrically connecting ones of said first plurality of contact means with ones of said third plurality of contact means;

means for electrically connecting ones of said second plurality of contact means with ones of said third plurality of contact means; and

means for urging said first electronic component against said first plurality of resilient contact means and said second plurality of resilient contact means.